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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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ISM43340-L77 Dual Band Wi-Fi ... BT4.0 ... Embedded SIP

*Integrates 2.4 GHz / 5 GHz Wi-Fi, IEEE 802.11 a/b/g/n
and Bluetooth 4.0 in a SINGLE system in a package.*

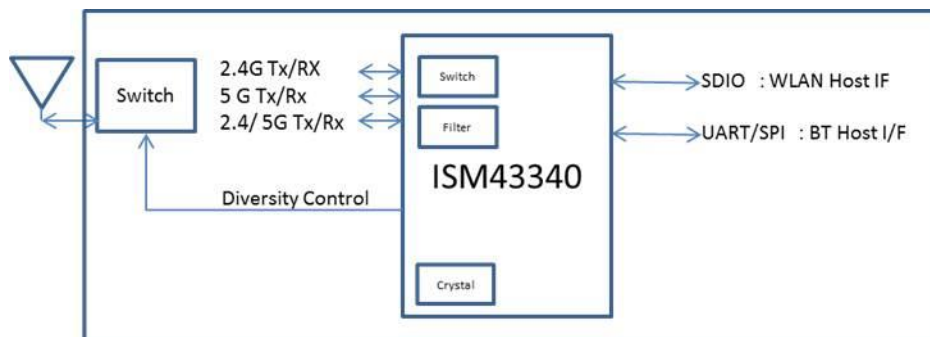
The Inventek ISM43340 SIP is designed based on Broadcom BCM43340 chipset solution. The ISM43340 single-chip quad-radio device provides the highest level of integration for a mobile or handheld wireless system, with integrated dual band (2.4 GHz / 5 GHz) IEEE 802.11 a/b/g and single-stream IEEE 802.11n MAC/baseband/radio and Bluetooth 4.0. The ISM43340 includes integrated power amplifiers, LNAs and T/R switches for the 2.4 GHz and 5 GHz WLAN bands, greatly reducing the external part count, PCB footprint, and cost of solutions.

Features:

The ISM43341 implements the highly sophisticated Enhanced Collaborative Coexistence algorithms and hardware mechanisms, allowing for an extremely collaborative Bluetooth coexistence scheme along with coexistence support for external radios (such as cellular and LTE, GPS, WiMAX, and Ultra-Wideband) and a single shared 2.4 GHz antenna for Bluetooth and WLAN. As a result, enhanced overall quality for simultaneous voice, video, and data transmission on a handheld system is achieved.



13 x 14 mm



For the WLAN section, two host interface options are included: an SDIO v2.0 interface (including gSPI) and a High-Speed Inter-Chip (HSIC) interface (a USB 2.0 derivative for short-distance on-board connections). An independent, high-speed UART is provided for the Bluetooth host interface.

IEEE 802.11x Key Features:

- Dual-band 2.4 GHz and 5 GHz IEEE 802.11 a/b/g/n
- Single-stream IEEE 802.11n supports for 20 MHz and 40 MHz channels provides PHY layer rates up to 150 Mbps for typical upper-layer throughput in excess of 90 Mbps
- Supports the 802.11n STBC (space-time block coding) RX and LDPC (low-density parity check) Tx options for improved range and power efficiency
- Supports a single 2.4 GHz antenna shared between WLAN and Bluetooth
- Supports standard SDIO v2.0 and gSPI (48 MHz) host interfaces
- Alternative host interface supports HSIC v1.0 (short-distance USB device)
- OneDriver™ software architecture for easy migration from existing embedded WLAN and Bluetooth devices as well as future devices

Bluetooth Features

- Support for ISO/IEC 18092, ISO/ IEC 21481,ISO/IEC 14443 Types A, B and B', Japanese Industrial Standard (JIS) (X) 6319-4, and ISO/IEC 15693 standards
- Bluetooth Core Specification 4.0
- Bluetooth Class 1 or Class 2 Transmitter
- Bluetooth Low energy support
- Bluetooth Smart Audio technology improves voice and music quality to headsets

Product Availability:

Part Number	Description
ISM43340-L77	2.4 / 5G Wi-Fi, Bluetooth SIP Module – Commercial Temp